





PDS-263-1 CTF-10G-4-SM

#### **FEATURES**

- + 4 channels (4 Tx, 4 Rx) 10GbE on single mode fiber converted bi-directionally to 4 channels of XAUI
- + D38999 Shell Size 25

#### FIBER INTERFACE

- + D38999 Shell Size 25 receptacle with CTF-QUAD single mode 1310 nm fiber
- + 4 Tx and 4 Rx 1310nm single mode fiber embedded into size 8 contacts with 1.25mm industry standard ceramic interface

# **COPPER INTERFACE**

+ Samtec Q Series High Speed Cable Assembly and vertical mount board connectors

> Two hanging cable assemblies for distributed connections across the subsystem and backplane

- + Low power consumption
- + MDIO serial interface for Built-In Test and Diagnostics

#### RUGGEDIZATION

- + Natural convection cooled (no fan
- + Operational temperature -40°C to +85°C
- + Storage temperature -50°C to +125°C
- + EMI/EMC compatible
- + Refer to page 4 for additional details

### CONTACT US:

Koji Shinozaki

E-mail: Shinozaki@amphenol.co.jp

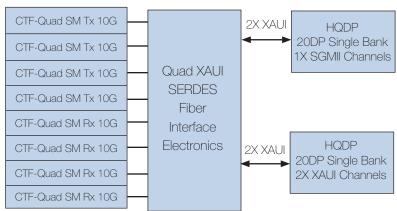
Phone: 045-473-9219

#### **OVERVIEW**

Amphenol Aerospace adds the CTF-10G-4-SM fiber to copper converter to the Integrated Electronics Product Line. This product line is rugged, flexible, and affordable with many options available

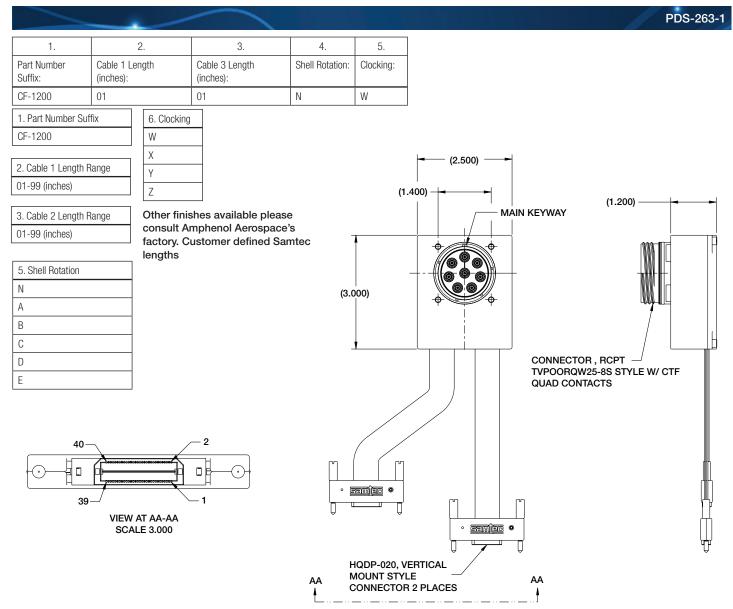
The converter is an integrated media converter and SERDES interfacing with both four channels of XAUI and four channels of single mode bi-directional 10G Ethernet





# CTF-10G-4-SM DRAWING





Test Cable for CF-020010-31NW = CF-901200-548

Mating Connector = CF-020012-001X

Test Board = CF-980062-035

Consult Amphenol Aerospace's Factory for other configurations.

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Samtec HQDP-020 (20 pairs; 40 Signals)1					
Pin	Description	Pin	Description		
1	CH1 XAUI 1 Tx+	2	CH2 XAUI 1 Tx+		
3	CH1 XAUI 1 Tx-	4	CH2 XAUI 1 Tx-		
5	CH1 XAUI 1 Rx+	6	CH2 XAUI 1 Rx+		
7	CH1 XAUI 1 Rx-	8	CH2 XAUI 1 Rx-		
9	CH1 XAUI 2 Tx+	10	CH2 XAUI 2 Tx+		
11	CH1 XAUI 2 Tx-	12	CH2 XAUI 2 Tx-		
13	CH1 XAUI 2 Rx+	14	CH2 XAUI 2 Rx+		
15	CH1 XAUI 2 Rx-	16	CH2 XAUI 2 Rx-		
17	CH1 XAUI 3 Tx+	18	CH2 XAUI 3 Tx+		
19	CH1 XAUI 3 Tx-	20	CH2 XAUI 3 Tx-		
21	CH1 XAUI 3 Rx+	22	CH2 XAUI 3 Rx+		
23	CH1 XAUI 3 Rx-	24	CH2 XAUI 3 Rx-		
25	CH1 XAUI 4 Tx+	26	CH2 XAUI 4 Tx+		
27	CH1 XAUI 4 Tx-	28	CH2 XAUI 4 Tx-		
29	CH1 XAUI 4 Rx+	30	CH2 XAUI 4 Rx+		
31	CH1 XAUI 4 Rx-	32	CH2 XAUI 4 Rx-		
33	5V Power	34	5V Power		
35	Ground	36	Ground		
37	MDIO	38	MDC		
39	LOS	40	Transmit Disable		
Ribbon Connector - QTH-020-01-H-D-DP-EM2					
Board Connector - QSH-020-01-H-D-DP-K					

Board connector must be used with SO-0165-04-01-02 screw mounts with correct spacing

Samtec HQDP-020 (20 pairs; 40 Signals)2						
Pin	Description	Pin	Description			
1	CH3 XAUI 1 Tx+	2	CH4 XAUI 1 Tx+			
3	CH3 XAUI 1 Tx-	4	CH4 XAUI 1 Tx-			
5	CH3 XAUI 1 Rx+	6	CH4 XAUI 1 Rx+			
7	CH3 XAUI 1 Rx-	8	CH4 XAUI 1 Rx-			
9	CH3 XAUI 2 Tx+	10	CH4 XAUI 2 Tx+			
11	CH3 XAUI 2 Tx-	12	CH4 XAUI 2 Tx-			
13	CH3 XAUI 2 Rx+	14	CH4 XAUI 2 Rx+			
15	CH3 XAUI 2 Rx-	16	CH4 XAUI 2 Rx-			
17	CH3 XAUI 3 Tx+	18	CH4 XAUI 3 Tx+			
19	CH3 XAUI 3 Tx-	20	CH4 XAUI 3 Tx-			
21	CH3 XAUI 3 Rx+	22	CH4 XAUI 3 Rx+			
23	CH3 XAUI 3 Rx-	24	CH4 XAUI 3 Rx-			
25	CH3 XAUI 4 Tx+	26	CH4 XAUI 4 Tx+			
27	CH3 XAUI 4 Tx-	28	CH4 XAUI 4 Tx-			
29	CH3 XAUI 4 Rx+	30	CH4 XAUI 4 Rx+			
31	CH3 XAUI 4 Rx-	32	CH4 XAUI 4 Rx-			
33	5V Power	34	5V Power			
35	Ground	36	Ground			
37	Spare	38	Spare			
39	LOS	40	Transmit Disable			
Ribbon Connector - QTH-020-01-H-D-DP-EM2						
Board Connector - QSH-020-01-H-D-DP-K						
Board connector must be used with SO-0165-04-						

01-02 screw mounts with correct spacing

MIL-DTL-38999 Shell Size 25 with CTF-QUAD						
Α	CH1 Tx	E	CH3 Tx			
В	CH1 Rx	F	CH3 Rx			
С	CH2 Tx	G	CH4 Tx			
D	CH2 Rx	Н	CH4 Rx			

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# AMPHENOL INTEGRATED ELECTRONIC PRODUCTS RUGGEDIZATION DESIGN



PDS-263-1

#### Overview

Amphenol integrated electronic products are designed and manufactured to our Ruggedization guidelines listed below. These guidelines ensure years of reliable operation in harsh environment applications where extreme operating temperatures, shock, vibration and corrosive atmospheres are regularly experienced

#### **Temperature**

- Operating Temperature Thermal Cycles between -40°C and 85°C while device is operating
- Temperature is measured at chassis housing or card edge
- Storage Temperature Thermal Cycles between -55°C and 125°C

#### Humidity

- Operating Humidity Humidity cycle between 0-100% non-condensing humidity while device is operating
- Storage Humidity Humidity cycle between 0-100% condensing humidity

#### Sealing

• Sealing can be optionally provided at the MIL-DTL-38999 interface with up to 10-5 cc/sec performance

#### Fluids Susceptibility

• MIL-DTL-38999 receptacle interface per EIA-364-10E

#### Vibration & Shock

- Sine Vibration 10 g Peak, 5-2,000Hz
  - -Based on a sine sweep duration of 10 minutes per axis in each of three mutually perpendicular axes. May be displacement limited from 5 to 44 Hz, depending on specific test.
- Random Vibration 0.005@5Hz, 0.1@15Hz, 0.1@2,000Hz
  - -60 minutes per axis, in each of three mutually perpendicular axes.
- 40 G Peak Shock Cycle
  - -Three hits in each axis, both directions, ½ sine and terminal-peak saw tooth, Total 36 hits.

#### Altitude

• -1,500 to 60,000 ft Altitude Testing w/ Rapid Depressurization

#### Electromagnetic Compatibility

• Designed to comply with MIL-STD-461E

#### **Printed Circuit Board Assemblies**

- Conformal Coat
  - -Amphenol performs Conformal Coating to both sides of printed circuit board assemblies using HUMISEAL IB31 in accordance with IPC-610, Class 3.
- Printed Circuit Board Rigidity
  - -Amphenol printed circuit boards are fabricated in accordance with IPC-6012, Class 3.
- Printed Circuit Board Fabrication
  - -Amphenol printed circuit boards acceptance criteria is in accordance with IPC-610, Class 3.

#### Reliability Predictions (MTBF)

Amphenol can perform Mean Time Between Failure (MTBF) reliability analysis in full compliance with MIL-HDBK-217F-1 Parts Count Prediction and MIL-HDBK-217F-1 Parts Stress Analysis Prediction. We can also perform reliability analyses in full compliance of ANSI/VITA 51.1 if it is required or preferred over the later method.

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